Title (en)
NO-RUB FINISHING COMPOSITIONS

Title (de)
REIBFREIER DECKLACK

Title (fr)
COMPOSITIONS DE FINITION SANS PON AGE

Publication
EP 1235864 A4 20030226 (EN)

Application
EP 00975438 A 20001027

Priority
• US 0029666 W 20001027
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Abstract (en)
[origin: US6632852B1] A self-leveling finishing composition capable of providing chemically resistant low profile coatings is described. The finishing composition comprises thermoplastic resin solids and thermosetting resin solids in a weight ratio of about 0.5:1 to about 11:1 and a solvent composition comprising a solvent capable of dissolving the thermoplastic resin solids component and a solvent miscible co-solvent capable of dissolving the thermosetting resin solids. The finishing composition is applied and dried to a dry-to-touch surface which is thereafter subjected to conditions capable of initiating polymerization of the component thermosetting resin solids. The finishing composition can be used as a substitute for more expensive or more labor intensive coating compositions in existing surface finishing protocols without compromise of surface quality and chemical resistance.</PTEXT>

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CPC (source: EP US)
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Citation (search report)
No further relevant documents disclosed

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WO 0130857 A1 20010503; AT E301138 T1 20050815; CA 2387396 A1 20010503; CA 2387396 C 20100216; DE 60021759 D1 20050908; DE 60021759 T2 20060601; EP 1235864 A1 20020904; EP 1235864 A4 20030226; EP 1235864 B1 20050803; ES 2249303 T3 20060401; MX PA02004051 A 20030922; US 6632852 B1 20031014

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